### **PRODUCT SPECIFICATIONS**

For Customer:		: APPRO	VAL FOR SPE	CIFICAT	TION
Customer Model No			: APPROVAL FOR SAMPLE		
Module No.:	ZC070IA0	2-40	Г	Date:202	21.08.13
			V	ersion :A	
1. Table o	f Conte	nts			
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Approved By		Comment			
PREPARED		CHECKED	VERIFIED B' DEPT	Y QA	VERIFIED BY R&D DEPT

#### 2. Revision Record

Date Rev.No.	Page Revision Items	Prepared
21.08.13 A	Thefirstrelease	
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#### 3. General Specifications

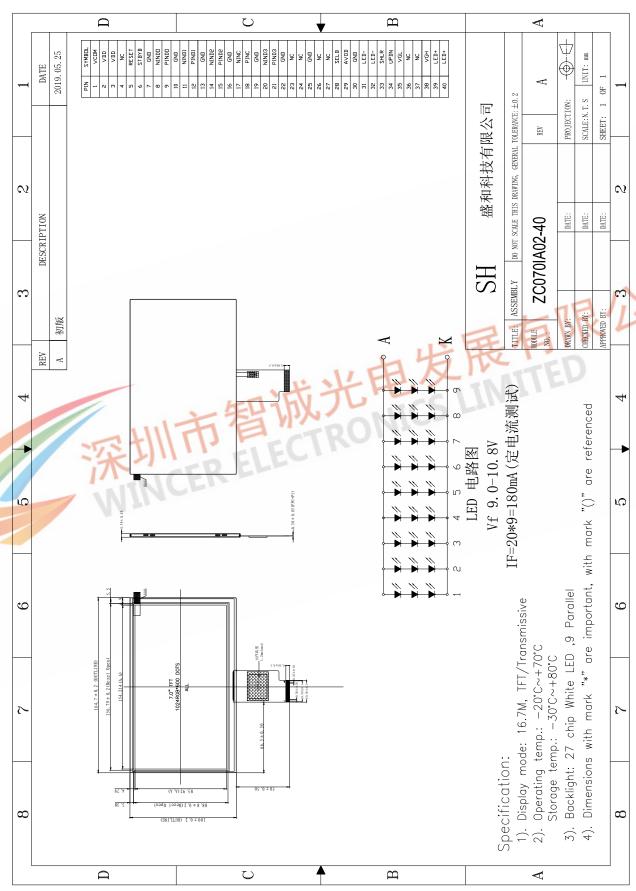
ZC070IA02-40 LisaTFT-LCDmodule.ItiscomposedofaTFT-LCDpanel, driver IC, FPC, a back light unit. The 7.0 "display area contains 1024 x 600 pixels and can display up to 16.7M colors. This product accords with RoHS environmental criterion.

Item	Contents	Unit	Note
LCD Type	Normally Black,Transmissive	-	
Display color	16.7M		1
Viewing Direction	ALL	O'Clock	事限"
Operating temperature	-20~+70七电力	C	(ED
Storage temperature	-30~+80	${f c}$	
Module size	165.00(W)×100.00(H)×3.50(T)	mm	2
Active Area(W×H)	154.2144(W)×85.92(H)	mm	
Number of Dots	1024×RGB×600	dots	
Backlight	27-LEDs (white)	pcs	
Interface	LVDS Interface	-	
Driver IC	HX8282-A11+HX8696-A		

Note 1: Color tune is slightly changed by temperature and driving voltage.

Note 2: Without FPC and Solder.

### 4. Outline. Drawing



### 5. Absolute Maximum Ratings(Ta=25°C)

#### 5.1 Electrical Absolute Maximum Ratings.(V<sub>SS</sub>=0V ,Ta=25℃)

Item	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	3.6	v
Analog Supply Voltage	AVDD	-0.5	14.85	V
TFT Gate ON Voltage	VGH	0.3	20	V
TFT Gate OFF Voltage	VGL	-20	0.3	V
TFT Common Electrode Voltage	VCOM	0	6	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	TST	-30	80	°C

#### Notes:

- 1. If the module is above these absolute maximum ratings. It may become permanently damaged.

  Using the module within the following electrical characteristic conditions are also exceeded, the
  - module will malfunction and cause poor reliability.
- 2. VDD>V<sub>SS</sub> must be maintained.
- 3. Please be sure users are grounded when handing LCD Module.

#### **5.2 Environmental Absolute Maximum Ratings.**

ltom	Storage		Operat	Note	
Item	MIN.	MAX.	MIN.	MAX.	Note
Ambient Temperature	-30℃	80℃	-20℃	70℃	1,2
Humidity	-	-	-	-	3

- 1. The response time will become lower when operated at low temperature.
- 2. Background color changes slightly depending on ambient temperature.

The phenomenon is reversible.

3. Ta<=40°C:85%RH MAX.

Ta>= $40^{\circ}$ C:Absolute humidity must be lower than the humidity of 85%RH at  $40^{\circ}$ C.

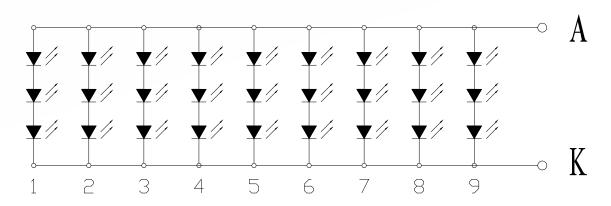
### 6. Electrical Specifications and Timing Characteristics

#### 6.1 Electrical characteristics(V<sub>SS</sub>=0V ,Ta=25°C)

Item	Symbol	Min.	Тур	Max.	Unit
Digital Supply Voltage	VDD	3.0	3.3	3.6	V
Analog Supply Voltage	AVDD	9.4	9.6	9.8	V
TFT Gate ON Voltage	VGH	-	17	-	V
TFT Gate OFF Voltage	VGL	-	-7	-	V
TFT Common Electrode Voltage	VCOM	-	5.35	建有	限

### 6.2 LED backlight specification(V<sub>SS</sub>=0V ,Ta=25℃)

Item	Symbol	Condition	Min	Тур	Max	Unit	Note
Supply voltage	CER	ELECI	9.0	9.6	10.8	V	1
Supply current	I <sub>f</sub>	-	-	180	-	mA	2



#### Note:

- 1: VLED=VLED(+)-VLED(-).
- 2:The current of LED is 20mA.

A LED drive in constant current mode is recommended.

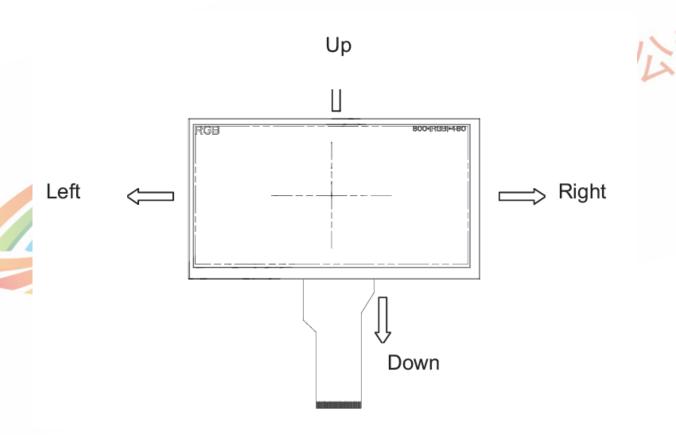
### 6.3 Interface signals

Pin NO.	Symbol	Description
1	VCOM	Common voltage
2~3	VDD	Digital Power
4	NC	No connection
5	Reset	Global reset pin. Active Low to enter Reset State. Normally pull high.  It's necessary to connecting with an RC delay circuit for stability.  (GRB delay VDD larger than 1ms)
6	STBYB	Standby mode, normally pull high STBYB=" 1", Normal Operation STBYB="0",Timing control, source driver will turn off, all output are high-Z
7	GND	Ground level for analog block.
8	NIND0	Negative LVDS Differential Data Inputs
9	PIND0	Positive LVDS Differential Data Inputs
10	GND	Ground
11	NIND1	Negative LVDS Differential Data Inputs
12	PIND1	Positive LVDS Differential Data Inputs
13	GND	Ground
14	NIND2	Negative LVDS Differential Data Inputs
15	PIND2	Positive LVDS Differential Data Inputs
16	GND	Ground
17	NINC	Negative LVDS Differential Clock Inputs
18	PINC	Positive LVDS Differential Clock Inputs
19	GND	Ground
20	NIND3	Negative LVDS Differential Data Inputs
21	PIND3	Positive LVDS Differential Data Inputs
22	GND	Ground
23~24	NC	No connection
25	GND	Ground
26~27	NC	No connection
28	SELB	6 bit/8 bit mode select
29	AVDD	Power for Analog Circuit
30	GND	Ground
31~32	LED-	LED Cathode
33	SHLR	Horizontal Inversion
34	UPDN	Vertical Inversion
35	VGL	Negative Power for TFT.
36~37	NC	No connection
38	VGH	Positive Power for TFT.
39~40	LED+	LED Anode

Note 4: Selection of scanning mode

Setting of scar	n control input	Scanning direction	
U/D	L/R	Scarring direction	
GND	$DV_{DD}$	Up to down, left to right	
$DV_{DD}$	GND	Down to up, right to left	
GND	GND	Up to down, right to left	
DV <sub>DD</sub>	$DV_DD$	Down to up, left to right	

Note 5: Definition of scanning direction. Refer to the figure as below:



Note 6: Global reset pin. Active low to enter reset state. Suggest to connect with an RC reset circuit for stability. Normally pull high.

Note 7:Dithering function enable control. Normally pull low DITHER = "1", Enable internal dithering function DITHER = "0", Disable internal dithering function

Note 8: Reserve for LED power input.

### 7. Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Brightness	Вр	<i>θ</i> =0°	-	600	-	Cd/m <sup>2</sup>	1
Uniformity	∠Bp	Ф=0°	75	80	-	%	1,2
	3:00		80	85	-		
Viewing	6:00	Cr≥10	80	85	-	Des	
Angle	9:00	CIZIO	80	85	-	Deg	3
	12:00		80	85	-		
Contrast Ratio	Cr	<i>θ</i> =0°	800	1000	-		4
Response Time	T <sub>r</sub> +T <sub>f</sub>	Ф=0°		25	35	ms5	旧
	X			0.309	\ E	起	bix
	W		17	0.330	过代	7	ED
	х	-11:4	计	0.614	cil	MIII	
Color of	R	<i>θ</i> =0°	TYP	0.340	TYP		4.0
CIE Coordinate	ET Ix	Ф=0°	-0.05	0.288	+0.05		1,6
17	Gy	FK		0.533			
V	х			0.138			
	В			0.136			

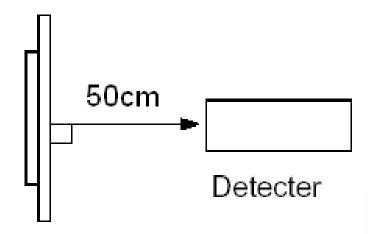
Note: The parameter is slightly changed by temperature, driving voltage and materiel

Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 (Φ8mm)

#### Measuring condition:

- Measuring surroundings: Dark room.
- Measuring temperature: Ta=25℃.
- Adjust operating voltage to get optimum contrast at the center of the display.

Measured value at the center point of LCD panel after more than 5 minutes while backlight turning on.

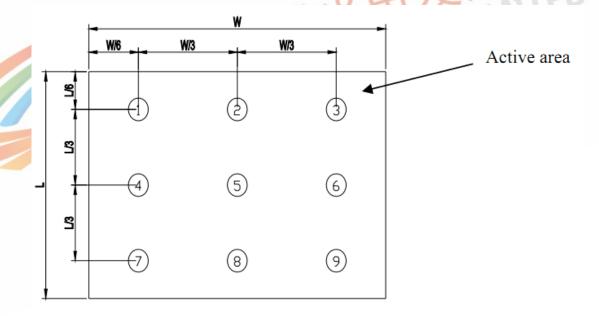


Note 2: The luminance uniformity is calculated by using following formula.

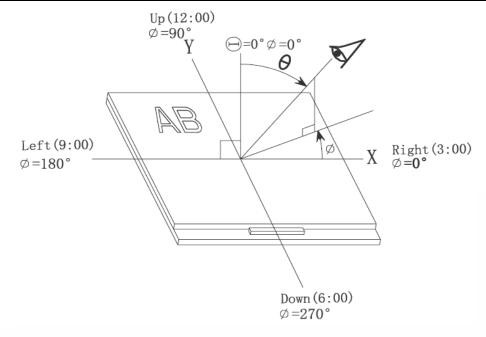
 $\angle$ Bp = Bp (Min.) / Bp (Max.)×100 (%)

Bp (Max.) = Maximum brightness in 9 measured spots

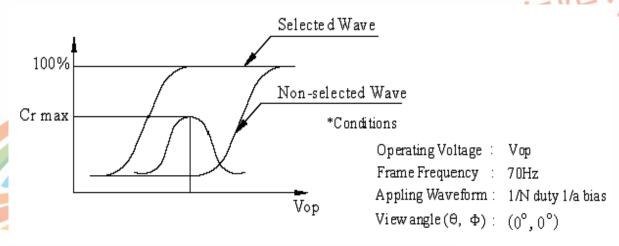
Bp (Min.) = Minimum brightness in 9 measured spots.



Note 3: The definition of viewing angle: Refer to the graph below marked by  $\theta$  and  $\Phi$ 



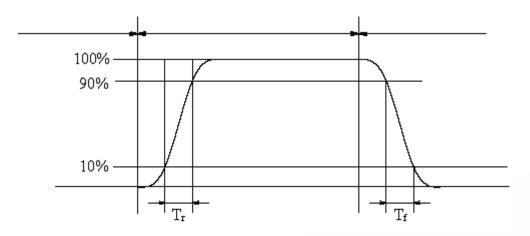
Note 4: Definition of contrast ratio.( Test LCD using DMS501)



$$Contrast \ ratio(Cr) = \frac{Brightness \ of \ selected \ dots}{Brightness \ of \ non-selected \ dots}$$

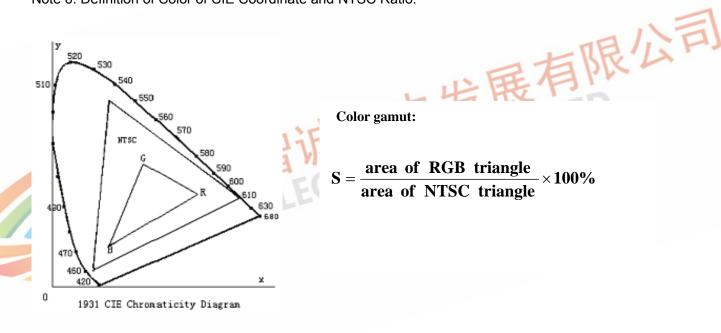
Note 5: Definition of Response time. (Test LCD using DMS501):

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.



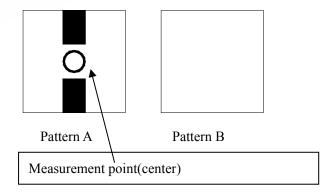
The definition of response time

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.



Note 7: Definition of cross talk.

Cross talk ratio(%)=|pattern A Brightness-pattern B Brightness|/pattern A Brightness\*100



Electric volume value=3F+/-3Hex

### 8. Reliability Test Items and Criteria

No	Test Item	Test condition	Criterion
1	High Temperature Storage	80℃±2℃ 96H Restore 2H at 25℃ Power off	
2	Low Temperature Storage	-30℃±2℃ 96H Restore 2H at 25℃ Power off	
3	High Temperature Operation	70℃±2℃ 96H Restore 2H at 25℃ Power on	1. After testing, cosmetic and electrical defects should not
4	Low Temperature Operation	-20℃±2℃ 96H Restore 4H at 25℃ Power on	happen.  2. Total current consumption should not be more than twice
5	High Temperature/Humidity Operation	50°C±2°C 90%RH 96H Power on	of initial value.
6	Temperature Cycle(Storage)	-20°C ←-25°C>70°C  30min 5min 30min  after 5 cycle, Restore 2H at 25°C  Power off	提付INITED
7	Vibration Test	10Hz~150Hz, 100m/s², 120min	Not allowed cosmetic
8	Shock Test	Half- sine wave,300m/s <sup>2</sup> ,11ms	and electrical defects.
9	ESD Test	Air discharge:+/-8KV, Contact discharge:4KV	

Note: Operation: Supply 3.3V for logic system.

The inspection terms after reliability test, as below

ITEM	Inspection
Contrast	CR>50%
IDD	IDD<200%
Brightness	Brightness>60%
Color Tone	Color Tone+/-0,05

### 9 Quality level

#### 9.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially

degrade usability for product applications, including all functional defects(such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

#### 9.2 Definition of inspection range

For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).

A area: center of viewing area

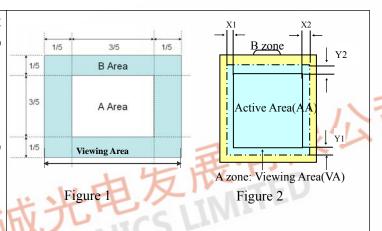
B area: periphery of viewing area

C area: Outside viewing area

For other defects, dividing two areas to make a judgment (according figure 2).

A zone: Inside Viewing area B zone: Outside Viewing area

X1(A.A~V.A): 2mm X2(A.A~V.A): 2mm Y1(A.A~V.A): 2mm Y2(A,A~V,A): 2mm



9.3 Inspection items and general notes						
	1.Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and SH.  2.Viewing area should be the area which SH guarantees.					
General notes	4 Viewing judgment should be junder static pattern					
Inspection items	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon doesn't change with voltage				
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage				
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass				
	Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when displ				
	Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction				

Glass defect	Glass crack, Shaved corner of glass, Surplus glass
PCB defect	Components assembly defect

### 9.4 Outgoing Inspection level

Outgoing Inspection	Inspection conditions	Inspection				
standard	mapection conditions	Min.	Max.	Unit	IL	AQL
Major Defects	See 8.3 general notes	See 8.5		П	0.065	
Minor Defects	Minor Defects See 8.3 general notes		See 8.5		Ш	0.065
Note: Sampling standard conforms to GB2828						

#### 9.5 Inspection Items and Criteria

				Judgmer	nt standard	根仏	
	Inspection items			Category	Acceptable number		
	-11		H	Category	A zone	B zone	
		训击智	Α	Ф<=0.20	Neglected	Neglected	
	Black spot, White	b	В	0.20<Ф<=0.25	3	Neglected	
	spot, Pinhole, Foreign	a →	С	0.25<Ф<=0.3	2	Neglected	
1	Particle, Particle in or on glass,	$\Phi = (a+b)/2 (mm)$	D	0.3<Ф<=0.4	1	3	
	Scratch on glass	(a/b<2.5)	Е	0.4<Ф<=0.5	0	2	
				tal defective point(B,C)	1	-	
		and Particle een rizer and s, Scratch on	Α	W<=0.03	Neglected	Neglected	
			В	0.03 <w<=0.05 L&lt;=3.0</w<=0.05 	3	Neglected	
2	Black line, White line, and Particle Between		С	0.05 <w<=0.1 L&lt;=3.0</w<=0.1 	2	Neglected	
P	Polarizer and glass, Scratch on glass		D	0.05 <w<=0.1 L&lt;=4.0</w<=0.1 	1	3	
			Е	W>0.1 L>4.0	0	2	
			Тс	tal defective point(B,C)	1	-	

3	Bright spot		any size		none	none		
	Contrast variation		Α	Ф<0.2	Neglected			
			В	0.2<Ф<=0.3	2	Noglostod		
4		b	С	0.3<Ф<=0.4	1	Neglected		
		$\Phi = (a+b)/2(mm)$	D	0.4<Ф	0			
			То	tal defective point(B,C)	3			
5	Bubble inside cell			any size	none	none		
	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.		Re	fer to item 1 and item 2.				
6	(if Polarizer is used)	Bubble, dent and convex	Α	Ф<=0.1	Neglected	Neglected		
			В	0.1 <Ф<=0.2	是省	Neglected		
			С	0.2 <Ф<=0.3	表1	2		
7	Surplus	Stage surplus glass	B<	=0.3mm	LIMILL			
1	glass	Surrounding surplus glass						
			Sh	ould not influence outline	dimension and ass	sembling.		
8	Open segment or o	Open segment or open common		Not permitted				
9	Short circuit		Not permitted					
10	0 False viewing direction		Not permitted					
11	Contrast ratio uneven		According to the limit specimen					
12	2 Crosstalk		According to the limit specimen					
13	Black /White spot(display)		Refer to item 1					
14	Black /White line(display)		Refer to item 2					

			Judgment standard	
Inspection items			Category(application: B zone)	Acceptable number
	i ) The front of lead terminals	В	a≤ t, b≤1/5W, c≤3mm  Crack at two sides of lead terminals should not cover patterns and alignment mark	
Glass 15 defect	ii ) Surrounding crack–non-contact side  seal  c b a t  Inner border line of the seal  Outer border line of the seal		Inner borderline of the seal	Max.3 defects
crack	seal  Inner border line of the seal Outer border line of the seal  iv) Corner	b <	Outer borderline of the seal $a \le t,  b \le 3.0,  c \le 3.0$	allowed
	w b c	В	Glass crack should not cover patterns u and alignment mark and patterns.	

		hadama and also also also		
	Inspection items	Judgment standard		
	1	Category(application: B zone)		
16 PCB defect	Component soldering: No cold soldering short open circuit burr, tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)  lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted  Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted  No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	Soldering pad Lead  L2>0  Component  L1>0  L2>0  L2>0  Base Board  Soldering tin is not permit in this area		
	Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat		

#### 10. Precautions for Use of LCD Modules

#### 10.1 Handling Precautions

- 10.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with RONICS LIN one of the following solvents:
  - Isopropyl alcohol
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 10.1.6 Do not attempt to disassemble the LCD Module.
- 10.1.7 If the logic circuit power is off, do not apply the input signals.
- 10.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
  - a. Be sure to ground the body when handling the LCD Modules.
  - b. Tools required for assembly, such as soldering irons, must be properly ground.
  - c. To reduce the amount of static electricity generated, do not conduct

assembly and other work under dry conditions.

d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

#### 10.2 Storage precautions

- 10.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 10.2.2 The LCD modules should be stored under the storage temperature range.

  If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :  $0^{\circ}$ C  $\sim 40^{\circ}$ C

Relatively humidity: ≤80%

- 10.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 10.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.